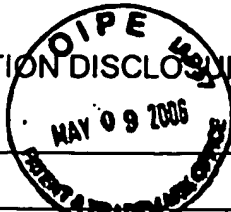


<div style="display: flex; justify-content: center; align-items: center;"> <div style="text-align: center; margin-right: 20px;">  </div> <div> <p style="font-size: 1.2em; margin: 0;">INFORMATION DISCLOSURE CITATION</p> </div> </div>				ATTY DOCKET NO. P-US075-A-MG		APPLICATION NO. 10/607,931	
				APPLICANT(S) Brown, et al.			
				FILING DATE June 27, 2003		GROUP ART UNIT 2817	
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<div style="display: flex; align-items: center;"> <div style="font-size: 2em; margin-right: 10px;">↓</div> <div style="border-left: 1px solid black; height: 100%;"></div> </div>	1	4,021,789	05/03/1977	Furman, et al.	365	182	
	2	4,127,831	11/28/1978	Gordon P. Riblet	333	10	
	3	4,958,222	09/18/1990	Kabushiki Kaisha Toshiba	357	84	
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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<div style="display: flex; align-items: center;"> <div style="font-size: 2em; margin-right: 10px;">↓</div> <div style="border-left: 1px solid black; height: 100%;"></div> </div>	8	2003/0127336	07/10/2003	Cohen, et al.	205	118	
	9	2003/0221968	12/04/2003	Cohen, et al.	205	118	
	10	2003/0222738	12/04/2003	Brown, et al.	333	160	
	11	2003/0234179	12/25/2003	Christopher A. Bang	205	118	
	12	2004/0000489	01/01/2004	Zhang, et al.	205	118	
	13	2004/0004001	01/08/2004	Cohen, et al.	205	118	
	14	2004/0004002	01/08/2004	Thompson, et al.	205	118	
	15	2004/0007468	01/15/2004	Cohen, et al.	205	118	
	16	2004/0065550	04/08/2004	Gang Zhang	205	135	
	17	2004/0020782	02/05/2004	Cohen, et al.	205	220	
	18	2004/0065555	04/08/2004	Gang Zhang	205	118	
EXAMINER /Kimberly Glenn/ (07/13/2006)				DATE CONSIDERED 07/13/2006			
<p><small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small></p>							

INFORMATION DISCLOSURE CITATION				ATTY DOCKET NO. P-US075-A-MG		APPLICATION NO. 10/607,931	
				APPLICANT(S) Brown, et al.			
				FILING DATE June 27, 2003		GROUP ART UNIT 2817	
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KG	19	EP 0313058	04/26/1989	Wong, Mon N.	H01Q	3/40	N/A
↓	20	JP 8-274167	10/18/1996				No - Abstract only
	21	JP 1-125956	05/18/1989				No - Abstract only
	22	JP 6-232217	08/19/1994				No - Abstract only
	23	RU 2046469	10/20/1995		H01P	5/18	No - Abstract only
	24	WO 2000/39854	07/06/2000	Kwon, et al.	H01L	27/00	N/A
	25	WO 2003/049514	06/12/2003	Brown, et al.	H05K	3/00	N/A
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KG	26		Cohen, et al., "EFAB: Batch Production of Functional, Fully-Dense Metal Parts with Micron-Scale Features", Proc. 9th Solid Freeform Fabrication, The University of Texas at Austin, August 1998, pg. 161.				
↓	27		Adam L. Cohen, et al., "EFAB: Rapid, Low-Cost Desktop Micromachining of High Aspect Ratio True 3-D MEMS", Proc. 12th IEEE Micro Electro Mechanical Systems Workshop, IEEE, Jan 1999, pg. 244.				
	28		"Microfabrication - Rapid Prototyping's Killer Application", Rapid Prototyping Report, CAD/CAM Publishing, Inc., June 1999, pgs. 1-5.				
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	33		F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", MEMS Symposium, ASME 1999 International Mechanical Engineering Congress and Exposition, November, 1999.				
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